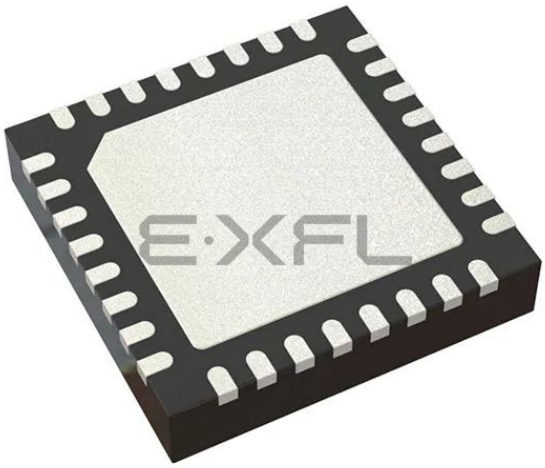

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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	ARM® Cortex®-M0+
Core Size	32-Bit Single-Core
Speed	48MHz
Connectivity	I²C, LINbus, SPI, UART/USART, USB
Peripherals	Brown-out Detect/Reset, DMA, I²S, POR, PWM, WDT
Number of I/O	26
Program Memory Size	256KB (256K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	32K x 8
Voltage - Supply (Vcc/Vdd)	1.62V ~ 3.6V
Data Converters	A/D 10x12b; D/A 1x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	32-VFQFN Exposed Pad
Supplier Device Package	32-VQFN (5x5)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/atsamd21e18a-mu

        - Up to four compare channels with optional complementary output
        - Generation of synchronized pulse width modulation (PWM) pattern across port pins
        - Deterministic fault protection, fast decay and configurable dead-time between complementary output
        - Dithering that increase resolution with up to 5 bit and reduce quantization error
    - 32-bit Real Time Counter (RTC) with clock/calendar function
    - Watchdog Timer (WDT)
    - CRC-32 generator
    - One full-speed (12Mbps) Universal Serial Bus (USB) 2.0 interface
        - Embedded host and device function
        - Eight endpoints
    - Up to six Serial Communication Interfaces (SERCOM), each configurable to operate as either:
        - USART with full-duplex and single-wire half-duplex configuration
        - I2C up to 3.4MHz
        - SPI
        - LIN slave
    - One two-channel Inter-IC Sound (I^2S) interface
    - One 12-bit, 350ksps Analog-to-Digital Converter (ADC) with up to 20 channels
        - Differential and single-ended input
        - 1/2x to 16x programmable gain stage
        - Automatic offset and gain error compensation
        - Oversampling and decimation in hardware to support 13-, 14-, 15- or 16-bit resolution
    - 10-bit, 350ksps Digital-to-Analog Converter (DAC)
    - Two Analog Comparators (AC) with window compare function
    - Peripheral Touch Controller (PTC)
        - 256-Channel capacitive touch and proximity sensing
- I/O
    - Up to 52 programmable I/O pins
- Drop in compatible with SAM D20
- Packages
    - 64-pin TQFP, QFN, UFBGA
    - 48-pin TQFP, QFN, WLCSP
    - 32-pin TQFP, QFN, WLCSP
- Operating Voltage
    - 1.62V – 3.63V

Ordering Code	FLASH (bytes)	SRAM (bytes)	Package	Carrier Type
ATSAMD21E16A-AU	64K	8K	TQFP32	Tray
ATSAMD21E16A-AUT				Tape & Reel
ATSAMD21E16A-AF				Tray
ATSAMD21E16A-AFT				Tape & Reel
ATSAMD21E16A-MU			QFN32	Tray
ATSAMD21E16A-MUT				Tape & Reel
ATSAMD21E16A-MF				Tray
ATSAMD21E16A-MFT				Tape & Reel
ATSAMD21E17A-AU	128K	16K	TQFP32	Tray
ATSAMD21E17A-AUT				Tape & Reel
ATSAMD21E17A-AF				Tray
ATSAMD21E17A-AFT				Tape & Reel
ATSAMD21E17A-MU			QFN32	Tray
ATSAMD21E17A-MUT				Tape & Reel
ATSAMD21E17A-MF				Tray
ATSAMD21E17A-MFT				Tape & Reel
ATSAMD21E18A-AU	256K	32K	TQFP32	Tray
ATSAMD21E18A-AUT				Tape & Reel
ATSAMD21E18A-AF				Tray
ATSAMD21E18A-AFT				Tape & Reel
ATSAMD21E18A-MU			QFN32	Tray
ATSAMD21E18A-MUT				Tape & Reel
ATSAMD21E18A-MF				Tray
ATSAMD21E18A-MFT				Tape & Reel

Ordering Code	FLASH (bytes)	SRAM (bytes)	Package	Carrier Type
ATSAMD21G18A-AU	256K	32K	TQFP48	Tray
ATSAMD21G18A-AUT				Tape & Reel
ATSAMD21G18A-AF				Tray
ATSAMD21G18A-AFT				Tape & Reel
ATSAMD21G18A-MU			QFN48	Tray
ATSAMD21G18A-MUT				Tape & Reel
ATSAMD21G18A-MF				Tray
ATSAMD21G18A-MFT				Tape & Reel
ATSAMD21G18A-UUT			WLCSP45	Tape & Reel

Table 3-5. Device Variant B

Ordering Code	FLASH (bytes)	SRAM (bytes)	Package	Carrier Type
ATSAMD21G15B-AU	32K	4K	TQFP48	Tray
ATSAMD21G15B-AUT				Tape & Reel
ATSAMD21G15B-AF				Tray
ATSAMD21G15B-AFT				Tape & Reel
ATSAMD21G15B-MU			QFN48	Tray
ATSAMD21G15B-MUT				Tape & Reel
ATSAMD21G15B-MF				Tray
ATSAMD21G15B-MFT				Tape & Reel
ATSAMD21G16B-AU	64K	8K	TQFP48	Tray
ATSAMD21G16B-AUT				Tape & Reel
ATSAMD21G16B-AF				Tray
ATSAMD21G16B-AFT				Tape & Reel
ATSAMD21G16B-MU			QFN48	Tray
ATSAMD21G16B-MUT				Tape & Reel
ATSAMD21G16B-MF				Tray
ATSAMD21G16B-MFT				Tape & Reel

Ordering Code	FLASH (bytes)	SRAM (bytes)	Package	Carrier Type
ATSAMD21J18A-AU	256K	32K	TQFP64	Tray
ATSAMD21J18A-AUT				Tape & Reel
ATSAMD21J18A-AF				Tray
ATSAMD21J18A-AFT				Tape & Reel
ATSAMD21J18A-MU			QFN64	Tray
ATSAMD21J18A-MUT				Tape & Reel
ATSAMD21J18A-MF				Tray
ATSAMD21J18A-MFT				Tape & Reel
ATSAMD21J18A-CU			UFBGA64	Tray
ATSAMD21J18A-CUT				Tape & Reel

Table 3-7. Device Variant B

Ordering Code	FLASH (bytes)	SRAM (bytes)	Package	Carrier Type
ATSAMD21J15B-AU	32K	4K	TQFP64	Tray
ATSAMD21J15B-AUT				Tape & Reel
ATSAMD21J15B-AF				Tray
ATSAMD21J15B-AFT				Tape & Reel
ATSAMD21J15B-MU			QFN64	Tray
ATSAMD21J15B-MUT				Tape & Reel
ATSAMD21J15B-MF				Tray
ATSAMD21J15B-MFT				Tape & Reel
ATSAMD21J16B-AU	64K	8K	TQFP64	Tray
ATSAMD21J16B-AUT				Tape & Reel
ATSAMD21J16B-AF				Tray
ATSAMD21J16B-AFT				Tape & Reel
ATSAMD21J16B-MU			QFN64	Tray
ATSAMD21J16B-MUT				Tape & Reel
ATSAMD21J16B-MF				Tray
ATSAMD21J16B-MFT				Tape & Reel
ATSAMD21J16B-CU			UFBGA64	Tray
ATSAMD21J16B-CUT				Tape & Reel

3.4 Device Identification

The DSU - Device Service Unit peripheral provides the Device Selection bits in the Device Identification register (DID.DEVSEL) in order to identify the device by software. The SAM D21 variants have a reset value of DID=0x1001drxx, with the LSB identifying the die number ('d'), the die revision ('r') and the device selection ('xx').

Table 3-8. SAM D21 Device Identification Values

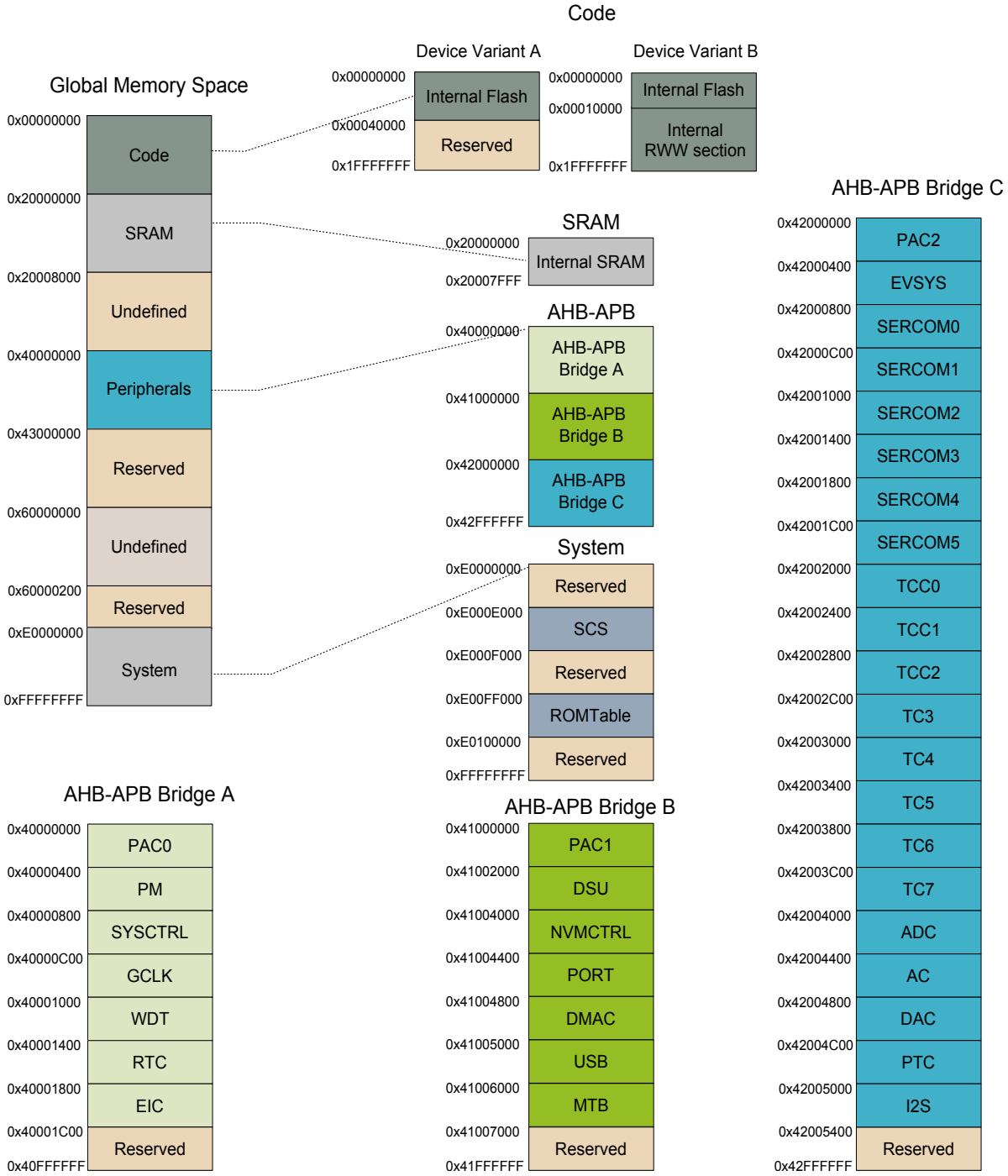
Device Variant	DID.DEVSEL	Device ID (DID)
SAMD21J18A	0x00	0x10010000
SAMD21J17A	0x01	0x10010001
SAMD21J16A	0x02	0x10010002
SAMD21J15A	0x03	0x10010003
Reserved	0x04	
SAMD21G18A	0x05	0x10010005
SAMD21G17A	0x06	0x10010006
SAMD21G16A	0x07	0x10010007
SAMD21G15A	0x08	0x10010008
Reserved	0x09	
SAMD21E18A	0x0A	0x1001000A
SAMD21E17A	0x0B	0x1001000B
SAMD21E16A	0x0C	0x1001000C
SAMD21E15A	0x0D	0x1001000D
Reserved	0x0E	
SAMD21G18A (WLCSP)	0x0F	0x1001000F
SAMD21G17A (WLCSP)	0x10	0x10010010
Reserved	0x11 - 0x1F	
SAMD21J16B	0x20	0x10011420
SAMD21J15B	0x21	0x10011421
Reserved	0x22	
SAMD21G16B	0x23	0x10011423
SAMD21G15B	0x24	0x10011424
Reserved	0x25	
SAMD21E16B	0x26	0x10011426
SAMD21E15B	0x27	0x10011427
Reserved	0x28-0x54	

Device Variant	DID.DEVSEL	Device ID (DID)
SAMD21E16B (WLCSP)	0x55	0x10011455
SAMD21E15B (WLCSP)	0x56	0x10011456
Reserved	0x57 - 0x61	
SAMD21E16C (WLCSP)	0x62	0x10011562
SAMD21E15C (WLCSP)	0x63	0x10011563
Reserved	0x64-0xFF	

Note: The device variant (last letter of the ordering number) is independent of the die revision (DSU.DID.REVISION): The device variant denotes functional differences, whereas the die revision marks evolution of the die. The device variant denotes functional differences, whereas the die revision marks evolution of the die.

6. Product Mapping

Figure 6-1. SAM D21 Product Mapping



This figure represents the full configuration of the SAM D21 with maximum flash and SRAM capabilities and a full set of peripherals. Refer to the Configuration Summary for details.

(INTFLAG) register. The interrupt flag is set when the interrupt condition occurs. Each interrupt in the peripheral can be individually enabled by writing a one to the corresponding bit in the peripheral's Interrupt Enable Set (INTENSET) register, and disabled by writing a one to the corresponding bit in the peripheral's Interrupt Enable Clear (INTENCLR) register. An interrupt request is generated from the peripheral when the interrupt flag is set and the corresponding interrupt is enabled. The interrupt requests for one peripheral are ORed together on system level, generating one interrupt request for each peripheral. An interrupt request will set the corresponding interrupt pending bit in the NVIC interrupt pending registers (SETPEND/CLRPEND bits in ISPR/ICPR). For the NVIC to activate the interrupt, it must be enabled in the NVIC interrupt enable register (SETENA/CLRENA bits in ISER/ICER). The NVIC interrupt priority registers IPR0-IPR7 provide a priority field for each interrupt.

Table 7-3. Interrupt Line Mapping

Peripheral Source	NVIC Line
EIC NMI – External Interrupt Controller	NMI
PM – Power Manager	0
SYSCTRL – System Control	1
WDT – Watchdog Timer	2
RTC – Real Time Counter	3
EIC – External Interrupt Controller	4
NVMCTRL – Non-Volatile Memory Controller	5
DMAC - Direct Memory Access Controller	6
USB - Universal Serial Bus	7
EVSYS – Event System	8
SERCOM0 – Serial Communication Interface 0	9
SERCOM1 – Serial Communication Interface 1	10
SERCOM2 – Serial Communication Interface 2	11
SERCOM3 – Serial Communication Interface 3	12
SERCOM4 – Serial Communication Interface 4	13
SERCOM5 – Serial Communication Interface 5	14
TCC0 – Timer Counter for Control 0	15
TCC1 – Timer Counter for Control 1	16
TCC2 – Timer Counter for Control 2	17
TC3 – Timer Counter 3	18
TC4 – Timer Counter 4	19
TC5 – Timer Counter 5	20
TC6 – Timer Counter 6	21
TC7 – Timer Counter 7	22
ADC – Analog-to-Digital Converter	23

Peripheral Source	NVIC Line
AC – Analog Comparator	24
DAC – Digital-to-Analog Converter	25
PTC – Peripheral Touch Controller	26
I2S - Inter IC Sound	27

7.3 Micro Trace Buffer

7.3.1 Features

- Program flow tracing for the Cortex-M0+ processor
- MTB SRAM can be used for both trace and general purpose storage by the processor
- The position and size of the trace buffer in SRAM is configurable by software
- CoreSight compliant

7.3.2 Overview

When enabled, the MTB records changes in program flow, reported by the Cortex-M0+ processor over the execution trace interface shared between the Cortex-M0+ processor and the CoreSight MTB-M0+. This information is stored as trace packets in the SRAM by the MTB. An off-chip debugger can extract the trace information using the Debug Access Port to read the trace information from the SRAM. The debugger can then reconstruct the program flow from this information.

The MTB simultaneously stores trace information into the SRAM, and gives the processor access to the SRAM. The MTB ensures that trace write accesses have priority over processor accesses.

The execution trace packet consists of a pair of 32-bit words that the MTB generates when it detects the processor PC value changes non-sequentially. A non-sequential PC change can occur during branch instructions or during exception entry. See the CoreSight MTB-M0+ Technical Reference Manual for more details on the MTB execution trace packet format.

Tracing is enabled when the MASTER.EN bit in the Master Trace Control Register is 1. There are various ways to set the bit to 1 to start tracing, or to 0 to stop tracing. See the CoreSight Cortex-M0+ Technical Reference Manual for more details on the Trace start and stop and for a detailed description of the MTB's MASTER register. The MTB can be programmed to stop tracing automatically when the memory fills to a specified watermark level or to start or stop tracing by writing directly to the MASTER.EN bit. If the watermark mechanism is not being used and the trace buffer overflows, then the buffer wraps around overwriting previous trace packets.

The base address of the MTB registers is 0x41006000; this address is also written in the CoreSight ROM Table. The offset of each register from the base address is fixed and as defined by the CoreSight MTB-M0+ Technical Reference Manual. The MTB has 4 programmable registers to control the behavior of the trace features:

- POSITION: Contains the trace write pointer and the wrap bit,
- MASTER: Contains the main trace enable bit and other trace control fields,
- FLOW: Contains the WATERMARK address and the AUTOSTOP and AUTOHALT control bits,
- BASE: Indicates where the SRAM is located in the processor memory map. This register is provided to enable auto discovery of the MTB SRAM location, by a debug agent.

See the CoreSight MTB-M0+ Technical Reference Manual for a detailed description of these registers.

Bit 1 – PM
Writing a zero to these bits has no effect.

Writing a one to these bits will clear the Write Protect bit for the corresponding peripherals.

Value	Description
0	Write-protection is disabled.
1	Write-protection is enabled.

7.6.2.2 PAC1 Register Description

Write Protect Clear

Name: WPCLR
Offset: 0x00
Reset: 0x000002
Property: –

Bit	31	30	29	28	27	26	25	24
Access								
Reset								

Bit	23	22	21	20	19	18	17	16
Access								
Reset								

Bit	15	14	13	12	11	10	9	8
Access								
Reset								

Bit	7	6	5	4	3	2	1	0
		MTB	USB		PORT	NVMCTRL	DSU	
Access		R/W	R/W		R/W	R/W	R/W	
Reset		0	0		0	0	1	

Bit 6 – MTB
Writing a zero to these bits has no effect.

Writing a one to these bits will clear the Write Protect bit for the corresponding peripherals.

Value	Description
0	Write-protection is disabled.
1	Write-protection is enabled.

Bit 5 – USB
Writing a zero to these bits has no effect.

Writing a one to these bits will clear the Write Protect bit for the corresponding peripherals.

Value	Description
0	Write-protection is disabled.
1	Write-protection is enabled.

Bit 3 – PORT
Writing a zero to these bits has no effect.

Writing a one to these bits will clear the Write Protect bit for the corresponding peripherals.

Value	Description
0	Write-protection is disabled.
1	Write-protection is enabled.

Bit 2 – NVMCTRL
Writing a zero to these bits has no effect.

Writing a one to these bits will clear the Write Protect bit for the corresponding peripherals.

Value	Description
0	Write-protection is disabled.
1	Write-protection is enabled.

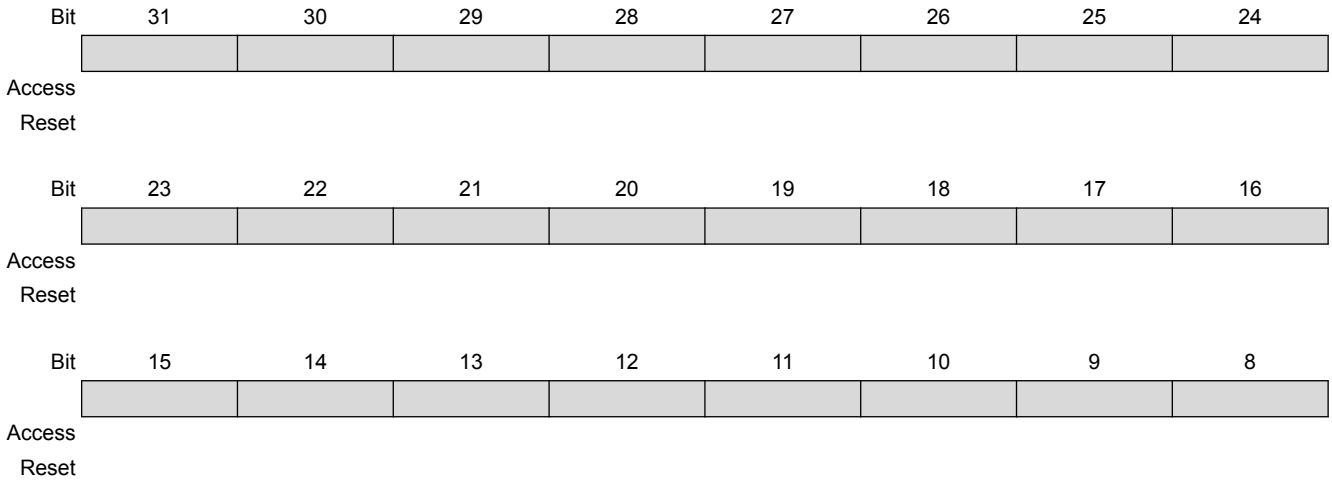
Bit 1 – DSU
Writing a zero to these bits has no effect.

Writing a one to these bits will clear the Write Protect bit for the corresponding peripherals.

Value	Description
0	Write-protection is disabled.
1	Write-protection is enabled.

Write Protect Set

Name: WPSET
Offset: 0x04
Reset: 0x000002
Property: –



Reset: 0x00800000
Property: –

Bit	31	30	29	28	27	26	25	24
Access								
Reset								

Bit	23	22	21	20	19	18	17	16
				I2S	PTC	DAC	AC	ADC
Access				R/W	R/W	R/W	R/W	R/W
Reset				0	0	0	0	0

Bit	15	14	13	12	11	10	9	8
	TC7	TC4	TC5	TC4	TC3	TCC2	TCC1	TCC0
Access	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
Reset	0	0	0	0	0	0	0	0

Bit	7	6	5	4	3	2	1	0
							EVSYS	
Access							R/W	
Reset							0	

Bit 20 – I2S
Writing a zero to these bits has no effect.

Writing a one to these bits will clear the Write Protect bit for the corresponding peripherals.

Value	Description
0	Write-protection is disabled.
1	Write-protection is enabled.

Bit 19 – PTC
Writing a zero to these bits has no effect.

Writing a one to these bits will clear the Write Protect bit for the corresponding peripherals.

Value	Description
0	Write-protection is disabled.
1	Write-protection is enabled.

Bit 18 – DAC:
Writing a zero to these bits has no effect.

Writing a one to these bits will clear the Write Protect bit for the corresponding peripherals.

Value	Description
0	Write-protection is disabled.
1	Write-protection is enabled.

Bit 17 – AC
Writing a zero to these bits has no effect.

Property: –

Bit	31	30	29	28	27	26	25	24
Access								
Reset								

Bit	23	22	21	20	19	18	17	16
				I2S	PTC	DAC	AC	ADC
Access				R/W	R/W	R/W	R/W	R/W
Reset				0	0	0	0	0

Bit	15	14	13	12	11	10	9	8
	TC7	TC6	TC5	TC4	TC3	TCC2	TCC1	TCC0
Access	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
Reset	0	0	0	0	0	0	0	0

Bit	7	6	5	4	3	2	1	0
	SERCOM5	SERCOM4	SERCOM3	SERCOM2	SERCOM1	SERCOM0	EVSYS	
Access	R/W	R/W	R/W	R/W	R/W	R/W	R/W	
Reset	0	0	0	0	0	0	0	

Bit 20 – I2S
Writing a zero to these bits has no effect.

Writing a one to these bits will clear the Write Protect bit for the corresponding peripherals.

Value	Description
0	Write-protection is disabled.
1	Write-protection is enabled.

Bit 19 – PTC
Writing a zero to these bits has no effect.

Writing a one to these bits will clear the Write Protect bit for the corresponding peripherals.

Value	Description
0	Write-protection is disabled.
1	Write-protection is enabled.

Bit 18 – DAC:
Writing a zero to these bits has no effect.

Writing a one to these bits will clear the Write Protect bit for the corresponding peripherals.

Value	Description
0	Write-protection is disabled.
1	Write-protection is enabled.

Bit 17 – AC
Writing a zero to these bits has no effect.

Writing a one to these bits will clear the Write Protect bit for the corresponding peripherals.

8. Packaging Information

8.1 Thermal Considerations

Related Links

Junction Temperature

8.1.1 Thermal Resistance Data

The following Table summarizes the thermal resistance data depending on the package.

Table 8-1. Thermal Resistance Data

Package Type	θ_{JA}	θ_{JC}
32-pin TQFP	64.7°C/W	23.1°C/W
48-pin TQFP	63.6°C/W	12.2°C/W
64-pin TQFP	60.9°C/W	12.2°C/W
32-pin QFN	40.9°C/W	15.2°C/W
48-pin QFN	32.0°C/W	10.9°C/W
64-pin QFN	32.5°C/W	10.7°C/W
35-ball WLCSP	41.8°C/W	2.26°C/W

8.1.2 Junction Temperature

The average chip-junction temperature, T_J, in °C can be obtained from the following:

1. $T_J = T_A + (P_D \times \theta_{JA})$
2. $T_J = T_A + (P_D \times (\theta_{HEATSINK} + \theta_{JC}))$

where:

- θ_{JA} = Package thermal resistance, Junction-to-ambient (°C/W), see Thermal Resistance Data
- θ_{JC} = Package thermal resistance, Junction-to-case thermal resistance (°C/W), see Thermal Resistance Data
- $\theta_{HEATSINK}$ = Thermal resistance (°C/W) specification of the external cooling device
- P_D = Device power consumption (W)
- T_A = Ambient temperature (°C)

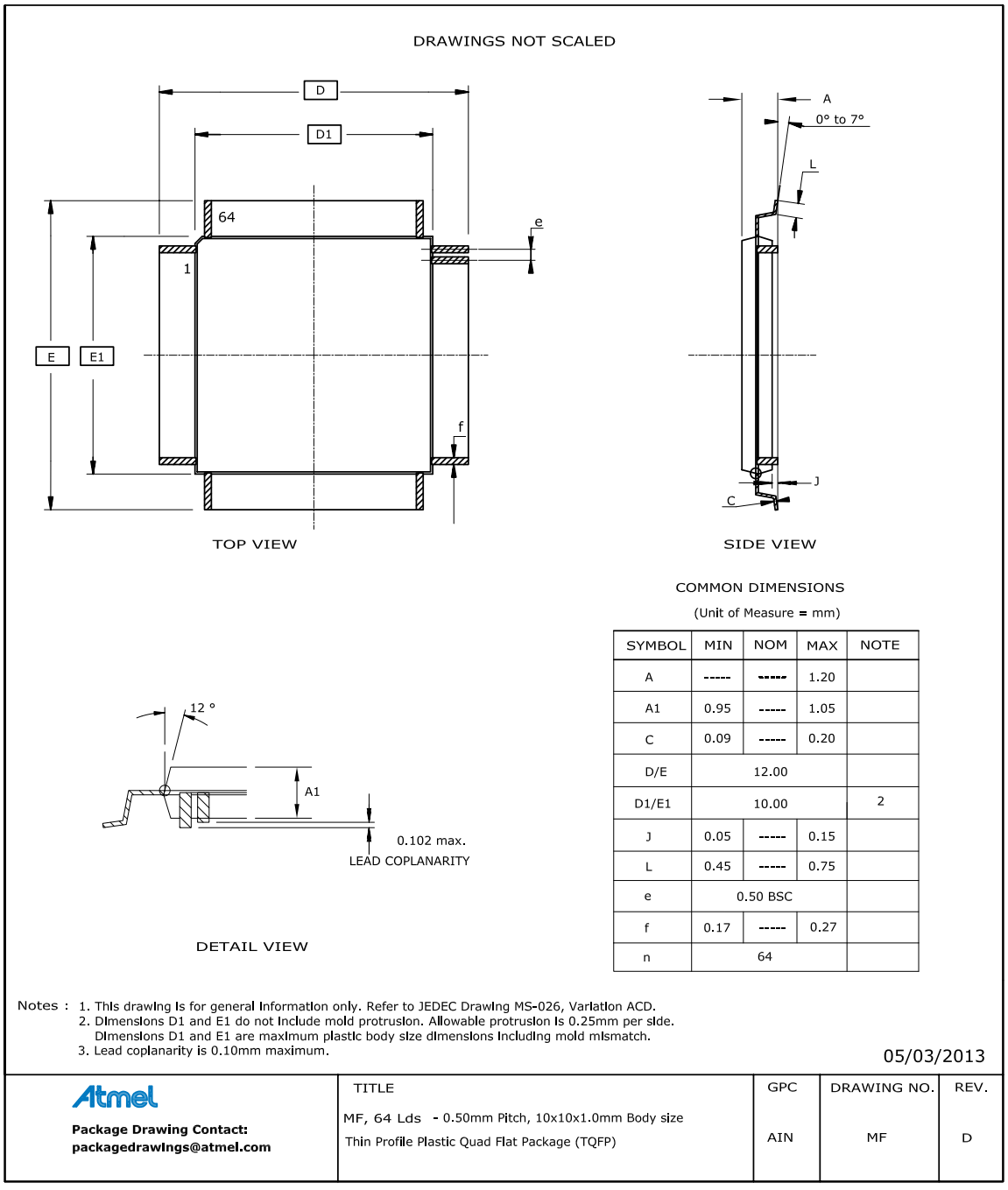
From the first equation, the user can derive the estimated lifetime of the chip and decide if a cooling device is necessary or not. If a cooling device is to be fitted on the chip, the second equation should be used to compute the resulting average chip-junction temperature T_J in °C.

Related Links

Thermal Considerations

8.2 Package Drawings

8.2.1 64 pin TQFP



COMMON DIMENSIONS

(Unit of Measure = mm)

SYMBOL	MIN	NOM	MAX	NOTE
A	-----	-----	1.20	
A1	0.95	-----	1.05	
C	0.09	-----	0.20	
D/E		12.00		
D1/E1		10.00		2
J	0.05	-----	0.15	
L	0.45	-----	0.75	
e		0.50 BSC		
f	0.17	-----	0.27	
n		64		

Notes : 1. This drawing is for general information only. Refer to JEDEC Drawing MS-026, Variation ACD.
2. Dimensions D1 and E1 do not include mold protrusion. Allowable protrusion is 0.25mm per side. Dimensions D1 and E1 are maximum plastic body size dimensions including mold mismatch.
3. Lead coplanarity is 0.10mm maximum.

05/03/2013

	TITLE	GPC	DRAWING NO.	REV.
Atmel **Package Drawing Contact:** **packagedrawings@atmel.com**	MF, 64 Lds - 0.50mm Pitch, 10x10x1.0mm Body size Thin Profile Plastic Quad Flat Package (TQFP)	AIN	MF	D

Table 8-2. Device and Package Maximum Weight

300	mg

Table 8-3. Package Characteristics

Moisture Sensitivity Level	MSL3

Table 8-5. Device and Package Maximum Weight

200	mg

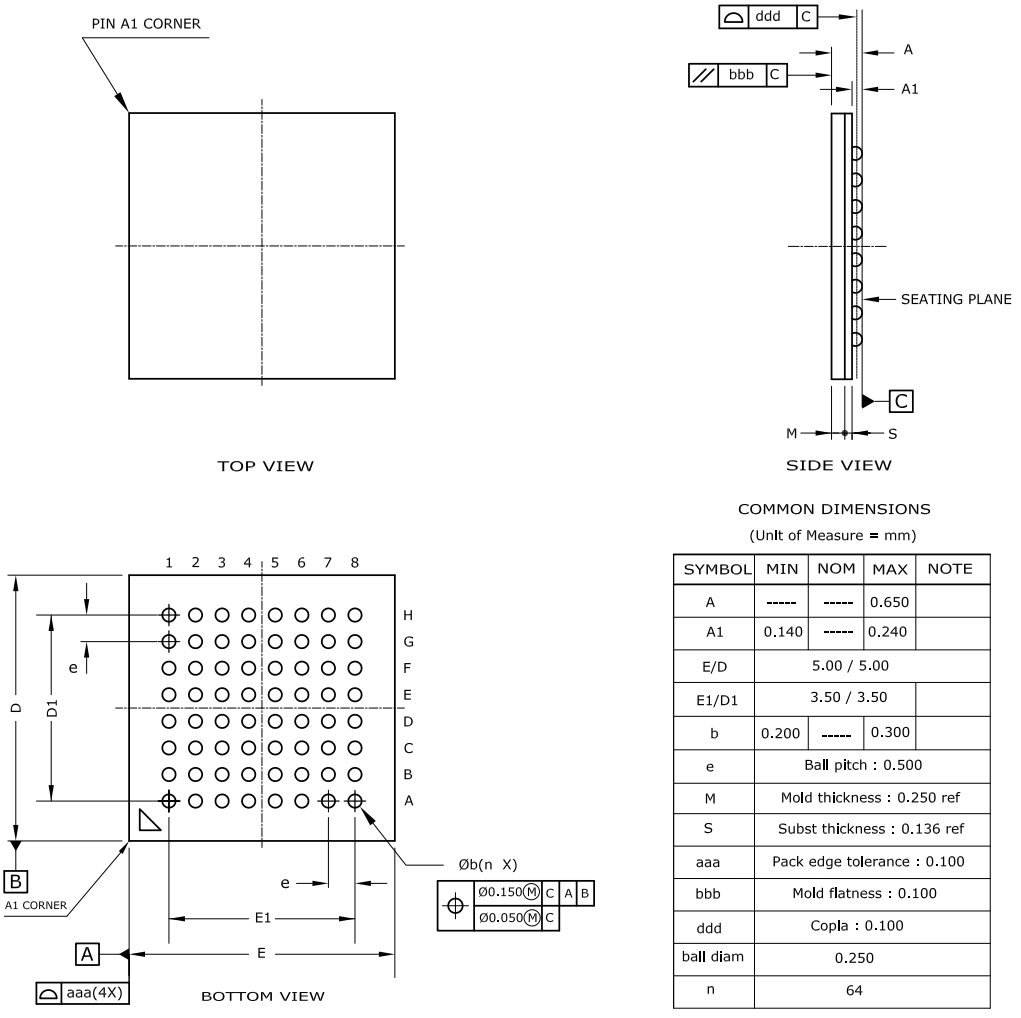
Table 8-6. Package Charateristics

Moisture Sensitivity Level	MSL3

Table 8-7. Package Reference

JEDEC Drawing Reference	MO-220
JESD97 Classification	E3

8.2.3 64-ball UFBGA



COMMON DIMENSIONS

(Unit of Measure = mm)

SYMBOL	MIN	NOM	MAX	NOTE
A	-----	-----	0.650	
A1	0.140	-----	0.240	
E/D	5.00 / 5.00			
E1/D1	3.50 / 3.50			
b	0.200	-----	0.300	
e	Ball pitch : 0.500			
M	Mold thickness : 0.250 ref			
S	Subst thickness : 0.136 ref			
aaa	Pack edge tolerance : 0.100			
bbb	Mold flatness : 0.100			
ddd	Copla : 0.100			
ball diam	0.250			
n	64			

Notes : 1. This drawing is for general information only. Refer to JEDEC Drawing MO-280, Variation UCCBB for proper dimensions, tolerances, datums, etc.
2. Array as seen from the bottom of the package.
3. Dimension A includes stand-off height A1, package body thickness, and lid height, but does not include attached features.
4. Dimension b is measured at the maximum ball diameter, parallel to primary datum C.

Table 8-8. Device and Package Maximum Weight

27.4	mg

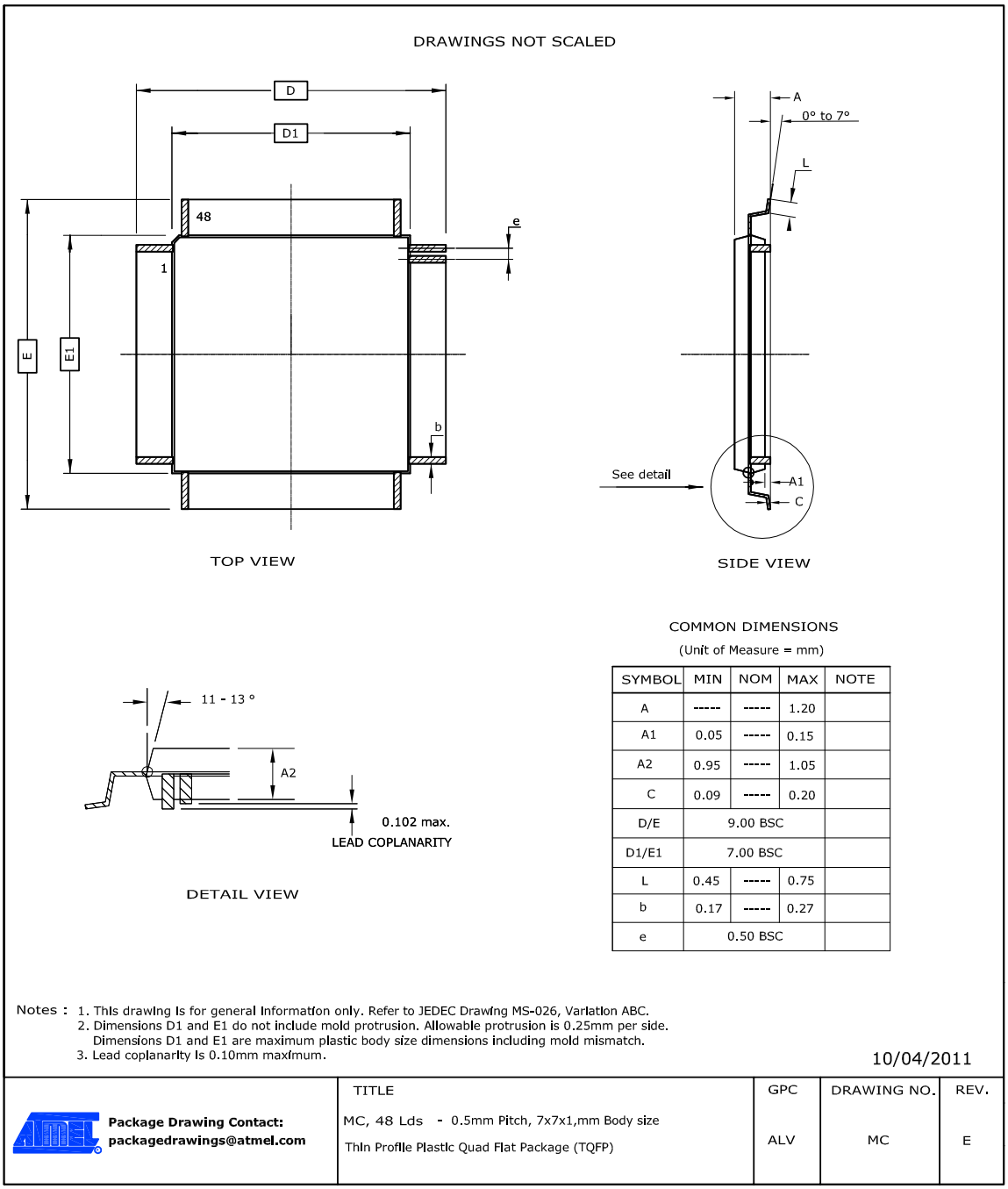
Table 8-9. Package Characteristics

Moisture Sensitivity Level	MSL3

Table 8-10. Package Reference

JEDEC Drawing Reference	MO-220
JESD97 Classification	E8

8.2.4 48 pin TQFP



COMMON DIMENSIONS

(Unit of Measure = mm)

SYMBOL	MIN	NOM	MAX	NOTE
A	-----	-----	1.20	
A1	0.05	-----	0.15	
A2	0.95	-----	1.05	
C	0.09	-----	0.20	
D/E	9.00 BSC			
D1/E1	7.00 BSC			
L	0.45	-----	0.75	
b	0.17	-----	0.27	
e	0.50 BSC			

Notes : 1. This drawing is for general information only. Refer to JEDEC Drawing MS-026, Variation ABC.
2. Dimensions D1 and E1 do not include mold protrusion. Allowable protrusion is 0.25mm per side. Dimensions D1 and E1 are maximum plastic body size dimensions including mold mismatch.
3. Lead coplanarity is 0.10mm maximum.

10/04/2011

	TITLE	GPC	DRAWING NO.	REV.
Package Drawing Contact: packagedrawings@atmel.com	MC, 48 Lds - 0.5mm Pitch, 7x7x1,mm Body size Thin Profile Plastic Quad Flat Package (TQFP)	ALV	MC	E

Table 8-11. Device and Package Maximum Weight

140	mg

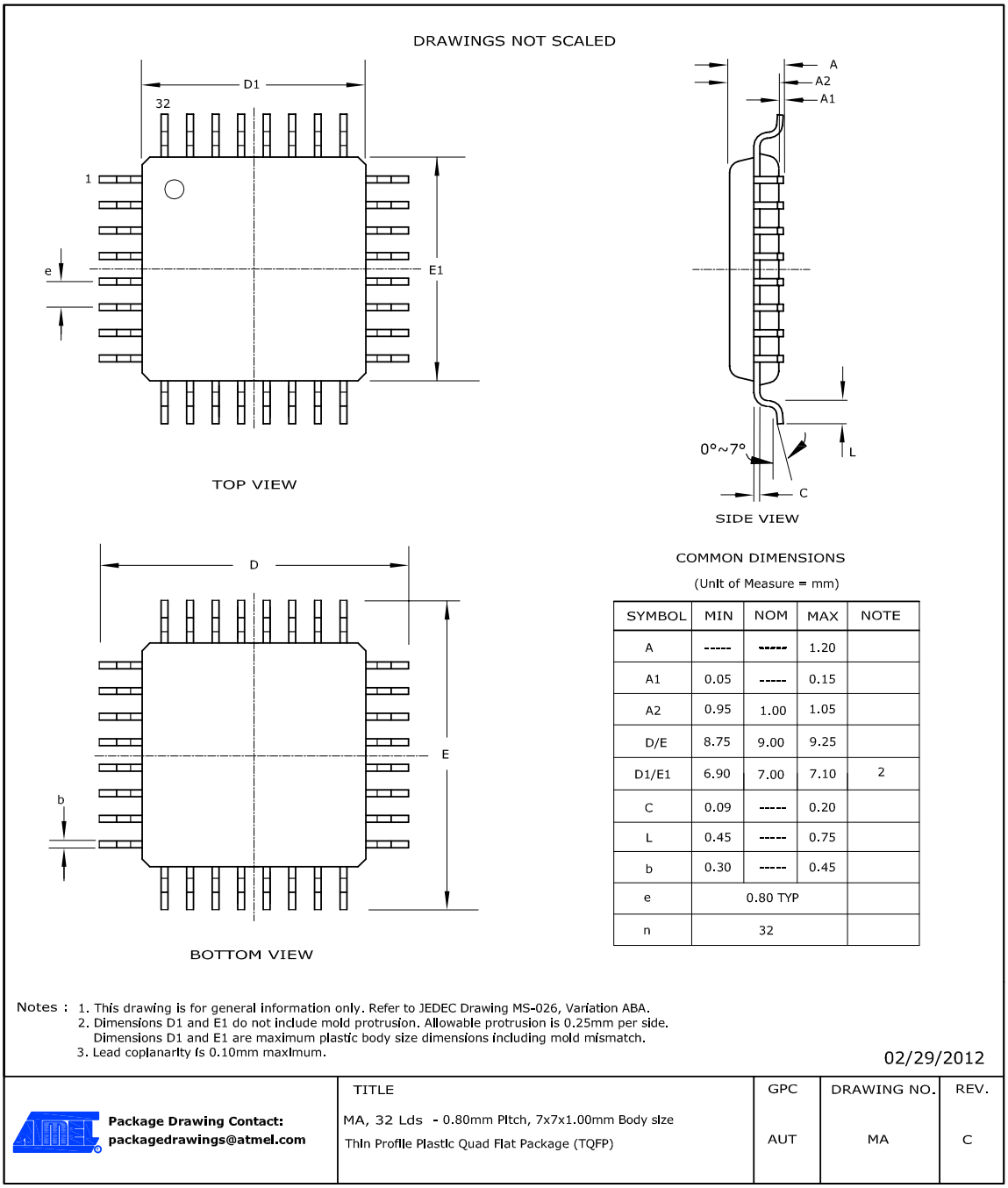
Table 8-12. Package Characteristics

Moisture Sensitivity Level	MSL3

Table 8-13. Package Reference

JEDEC Drawing Reference	MS-026
JESD97 Classification	E3

8.2.7 32 pin TQFP



COMMON DIMENSIONS

(Unit of Measure = mm)

SYMBOL	MIN	NOM	MAX	NOTE
A	-----	-----	1.20	
A1	0.05	-----	0.15	
A2	0.95	1.00	1.05	
D/E	8.75	9.00	9.25	
D1/E1	6.90	7.00	7.10	2
C	0.09	-----	0.20	
L	0.45	-----	0.75	
b	0.30	-----	0.45	
e	0.80 TYP			
n	32			

Notes : 1. This drawing is for general information only. Refer to JEDEC Drawing MS-026, Variation ABA.
2. Dimensions D1 and E1 do not include mold protrusion. Allowable protrusion is 0.25mm per side. Dimensions D1 and E1 are maximum plastic body size dimensions including mold mismatch.
3. Lead coplanarity is 0.10mm maximum.

02/29/2012

Package Drawing Contact: packagedrawings@atmel.com	TITLE	GPC	DRAWING NO.	REV.
	MA, 32 Lds - 0.80mm Pitch, 7x7x1.00mm Body size Thin Profile Plastic Quad Flat Package (TQFP)	AUT	MA	C

Table 8-20. Device and Package Maximum Weight

100	mg

Table 8-21. Package Charateristics

Moisture Sensitivity Level	MSL3

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